

WHAT IS CLAIMED IS:

1. A semiconductor device comprising:
an insulating film comprising silicon oxide on an insulating surface,
wherein the insulating film includes halogen at a concentration of $5 \times 10^{20} \text{ cm}^{-3}$
or less and carbon at a concentration of $5 \times 10^{19} \text{ cm}^{-3}$ or less which are detected by second ion
mass spectroscopy.
2. A device according to claim 1, wherein the halogen is chlorine.
3. A device according to claim 1, wherein the halogen is fluorine.
4. A device according to claim 1,
wherein the insulating film includes carbon at a concentration of $1 \times 10^{18} \text{ cm}^{-3}$
or less which is detected by the second ion mass spectroscopy.
5. A device according to claim 1,
wherein the insulating film includes halogen at a concentration of $1 \times 10^{17} \text{ cm}^{-3}$
or more which is detected by the second ion mass spectroscopy.
6. A device according to claim 1,
wherein the insulating film is a gate insulating film.
7. A device according to claim 1,
wherein the insulating film is an insulating film in a thin film transistor.
8. A device according to claim 1,
wherein the insulating film covers an even surface over a glass substrate.

9. A device according to claim 1,
 wherein the insulating film is formed by plasma chemical vapor deposition using an organic silane.

10. A device according to claim 9,
 wherein the organic silane comprises at least a material selected from the group consisting of $\text{Si}(\text{OC}_2\text{H}_5)_4$, $\text{Si}_2\text{O}(\text{OC}_2\text{H}_5)_6$, $\text{Si}_3\text{O}_2(\text{OC}_2\text{H}_5)_8$, $\text{Si}_4\text{O}_3(\text{OC}_2\text{H}_5)_{10}$ and $\text{Si}_5\text{O}_4(\text{OC}_2\text{H}_5)_{12}$.

11. A semiconductor device comprising:
 a crystalline semiconductor island on an insulating surface; and
 an insulating film including silicon oxide to cover the crystalline semiconductor island,
 wherein the insulating film includes halogen at a concentration of $5 \times 10^{20} \text{ cm}^{-3}$ or less and carbon at a concentration of $5 \times 10^{19} \text{ cm}^{-3}$ or less.

12. A device according to claim 11,
 wherein the concentrations of halogen and carbon are detected by secondary ion mass spectroscopy.

13. A device according to claim 11, wherein the halogen is chlorine.

14. A device according to claim 11, wherein the halogen is fluorine.

15. A device according to claim 11,
 wherein the insulating film includes carbon at a concentration of $1 \times 10^{18} \text{ cm}^{-3}$ or less.

16. A device according to claim 11,
wherein the insulating film includes halogen at a concentration of $1 \times 10^{17} \text{ cm}^{-3}$
or more.
17. A device according to claim 11,
wherein the insulating film is formed by plasma chemical vapor deposition
using an organic silane.
18. A device according to claim 17,
wherein the organic silane comprises at least a material selected from the group
consisting of $\text{Si}(\text{OC}_2\text{H}_5)_4$, $\text{Si}_2\text{O}(\text{OC}_2\text{H}_5)_6$, $\text{Si}_3\text{O}_2(\text{OC}_2\text{H}_5)_8$, $\text{Si}_4\text{O}_3(\text{OC}_2\text{H}_5)_{10}$ and
 $\text{Si}_5\text{O}_4(\text{OC}_2\text{H}_5)_{12}$.
19. A semiconductor device including at least a thin film transistor comprising:
a crystalline semiconductor island on an insulating surface;
a silicon oxide film over the crystalline semiconductor island; and
a conductive film including at least one of aluminum, titanium, and titanium
nitride, said conductive film being formed on the silicon oxide film,
wherein the silicon oxide film includes halogen at a concentration of 5×10^{20}
 cm^{-3} or less and carbon at a concentration of $5 \times 10^{19} \text{ cm}^{-3}$ or less.
20. A device according to claim 19,
wherein the concentrations of halogen and carbon are detected by secondary
ion mass spectroscopy.
21. A device according to claim 19, wherein the halogen is chlorine.
22. A device according to claim 19, wherein the halogen is fluorine.

30. A device according to claim 27, wherein the halogen is fluorine.
31. A device according to claim 27,
wherein the gate insulating film includes carbon at a concentration of 1×10^{18} cm^{-3} or less.
32. A device according to claim 27,
wherein the gate insulating film includes halogen at a concentration of 1×10^{17} cm^{-3} or more.
33. A device according to claim 27,
wherein the gate insulating film is formed by plasma chemical vapor deposition using an organic silane.
34. A device according to claim 33,
wherein the organic silane comprises at least a material selected from the group consisting of $\text{Si}(\text{OC}_2\text{H}_5)_4$, $\text{Si}_2\text{O}(\text{OC}_2\text{H}_5)_6$, $\text{Si}_3\text{O}_2(\text{OC}_2\text{H}_5)_8$, $\text{Si}_4\text{O}_3(\text{OC}_2\text{H}_5)_{10}$ and $\text{Si}_5\text{O}_4(\text{OC}_2\text{H}_5)_{12}$.